L Number	Hits	Search Text	DB	Time stamp
1	1359	((lower bottom) near electrode) with ((sacrificial oxide) near (layer	USPAT;	2004/06/18 10:35
		film)) with substrate	US-PGPUB;	
		<i>''</i>	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
2	41	(((lower bottom) near electrode) with ((sacrificial oxide) near (layer	USPAT;	2004/06/18 11:09
		film)) with substrate) and ((contact near (hole via open\$3)) near2	US-PGPUB;	
		(conductive near (layer film)))	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
3	4	((lower bottom) near electrode) with ((sacrificial near oxide) near (layer	USPAT;	2004/06/18 12:06
		film)) with substrate	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
4	923	((sacrificial near oxide) near (layer film)) with substrate	USPAT;	2004/06/18 10:42
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
5	262	((sacrificial near oxide) near (layer film)) near2 substrate	USPAT;	2004/06/18 10:42
			US-PGPUB;	
		×	ЕРО; ЛРО;	
			DERWENT;	
		(4) (5) (1) (1) (1) (2) (1) (1) (1) (1)	IBM_TDB	2004/06/19 10:42
6	13	(((sacrificial near oxide) near (layer film)) near2 substrate) and ((lower	USPAT;	2004/06/18 10:42
		bottom) near electrode)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
7	37	(((sacrificial near oxide) near (layer film)) near2 substrate) and (contact	USPAT;	2004/06/18 12:01
'	37	near (hole via open\$3))	US-PGPUB;	200 1700/10 12:01
		near (note via openius))	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
8	0	(((sacrificial near oxide) near (layer film)) near2 substrate) and ((contact	USPĀT;	2004/06/18 12:02
		near (hole via open\$3)) near2 electroplate)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
9	1	((fill\$3 near contact near (hole via open\$3)) near2 electroplate)	USPAT;	2004/06/18 13:08
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	2004/06/20 22 62
10	2	((contact near (hole via open\$3)) near2 electroplate)	USPAT;	2004/06/18 12:05
			US-PGPUB;]
			EPO; JPO;	
			DERWENT;	
, ,	_	((IBM_TDB	2004/06/19 12:05
11	2	((contact near (hole via open\$3)) with electroplate)	USPAT;	2004/06/18 12:05
]			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	275	((contact near (hole via open\$3)) and electroplate)	USPAT;	2004/06/18 12:06
12	213	(Contract fical (finite via openios)) and electropiate)	US-PGPUB;	2007/00/10 12:00
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
			1111	L

13	86	(((contact near (hole via open\$3)) and electroplate)) and capacitor\$1	USPAT;	2004/06/18 13:09
1 13	30		US-PGPUB;	200 1/00/10 15.07
	· ·		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	26	((((contact near (hole via open\$3)) and electroplate)) and capacitor\$1)	USPAT;	2004/06/18 12:06
17	20	and ((lower bottom) near electrode)	US-PGPUB;	200 110 12.00
		mid ((10 wer bottom) near electrode)	ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
15	1	(((depost\$3 fill\$3) near contact near (hole via open\$3)) near2	USPAT;	2004/06/18 13:10
1.5	•	electroplate)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
17	1	(depost\$3 fill\$3) and ((contact near (hole via open\$3)) near2	USPAT;	2004/06/18 13:10
*′	•	electroplate)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
16	267	(((contact near (hole via open\$3)) and electroplate)) and (deposit\$3	USPAT;	2004/06/18 13:36
"		fill\$3)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
18	26	etch\$3 with (gas\$2 near5 (O2 oxygen Cl2 BCl3 Ar HBr) near5 ((top	USPĀT;	2004/06/18 13:59
		upper) near electrode))	US-PGPUB;	
		*** / //	ЕРО, ЛРО,	
			DERWENT;	
			IBM_TDB	
19	2	("6376386").PN.	USPAT;	2004/06/18 13:39
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
20	0	etch\$3 with (gas\$2 near2 (O2 oxygen) near5 (Cl2 BCl3 Ar HBr) near5	USPAT;	2004/06/18 13:59
		((top upper) near electrode))	US-PGPUB;	
1			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	